



News Release

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Sales of Twin Stage Super-speed Package Singulation System “PS280” Commence

Tokyo Seimitsu Co., Ltd. (President, C.E.O. & C.O.O.: Sadakatsu Suzuki) begins sales of new dicing machine “PS280” which singulates CSP (Chip Scale Package) substrates including BGA and QFN substrates by diamond blades.

“PS280” is a system that connects picking and placing equipment (handler) and enables to cut and unload substrates automatically. In conventional systems of this process, the throughput was limited by the dicing part that has lower speed. Whereas, new “PS280” can bring super-speed solution to this bottleneck, with patent protected mechanism that integrates two independently auto-aligned stages.

[Features of “PS280”]

1: High Throughput

“PS280” specifications enable to double the handling speed to the conventional models and improve overall performance of the process drastically.

2: Auto Alignment

Independent auto-alignment function is activated in one stage, during cutting process is performed in another stage. This concept maximized twin stages' performance.

3: Twin High Power Spindle

“PS280” incorporates 2 high-power DC brush-less spindle motors on each axis, enabling powerful blade rotation for high-speed cutting even on CSP substrates.

[Target]

Package singulation market is expanding rapidly as it is low-cost and high-precision production system for CSP memory devices without using dicing tape. The market size is estimated to reach 30 billion yen in 2008.

Sales Starts: September 2007

